



CALL FOR PAPERS

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Due to the COVID-19 Pandemic, IEEE MTT-S has approved changing the original dates of LAMC 2020, now celebrating it in May 26-28, 2021, in an attempt to make it face-to face, but keeping the possibility to going virtual. IEEE MTT-S reconfirmed Cali, Colombia, as the venue for the 3rd IEEE MTT-S Latin America Microwave Conference (now LAMC 2021). During the past decade, Cali has gained national and international recognition for its potential to become one of the most important cities in Latin America and the Pacific in terms of logistics, manufacturing and creative industry. Cali, main city of the Pacific region of Colombia, known as a commercial, service and cultural hub, offers a vivid and dynamic environment for creation of innovative solutions, a wide variety of economic sectors, including both small and large companies as well as agricultural industry, a growing ICT ecosystem and high-quality universities. Looking for synergy, LAMC 2021 will be co-located with IEEE Colcom 2021 (IEEE Colombian Conference on Communications and Computing). We encourage the submission of original, unpublished research focused on (but not limited to) the following topics of interest:

- Passive components, circuits and devices** (planar and nonplanar components and circuits, filters and multiplexers, tunable devices, and metamaterials).
- Active components and measurements systems** (RFICs & MMIC design, power amplifiers, linearization techniques, low-noise circuits, signal generation, conversion & control modules, linear and non-linear modeling and characterization).
- RF systems and applications** (microwave systems and front-ends industrial scientific and medical applications, navigation systems, intelligent transportation systems, imaging, sensors, wireless power transmission).
- Communication systems** (terrestrial, vehicular, satellite and indoor applications, wireless and cellular communication systems).
- Active antennas** (phase arrays, integrated antennas, smart antennas, digital-beam forming and MIMO).
- Signal-power integrity and high-speed digital techniques** (EM interference and compatibility, high speed interconnects, post-silicon validation techniques, power delivery networks, computer simulations and measurements).
- CAD techniques for RF and microware engineering** (surrogate –based modeling and optimization, space mapping-based methods, model order reduction techniques, statistical analysis and design, EM based and multi physics design optimization, EM field theory, time and frequency-domain numerical techniques).

IMPORTANT DATES

Proposals for special sessions and tutorials:	December 20, 2020
Submission regular papers:	January 25, 2021
Notification:	March 1, 2021
Camera-ready	March 22, 2021
Author registration:	March 22, 2021

PAPER SUBMISSION

Papers submitted to LAMC 2021 will be peer reviewed and evaluated based on originality, quantitative contents, clarity, and interest to the audience. The review process will be single-blind. LAMC will use EDAS as the electronic paper management system. All accepted and presented papers will be published in the LAMC Conference Proceedings and submitted for inclusion in the IEEE Xplore Digital Library.

English will be the official language of the conference. Prospective authors are cordially invited to submit a three-page two-column manuscript (maximum 4 pages), following the instructions available at the conference website.